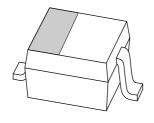
DISCRETE SEMICONDUCTORS

DATA SHEET



PMEG2010EALow V_F (MEGA) Schottky barrier diode

Product specification Supersedes data of 2002 Dec 10 2004 Feb 06





Low V_F (MEGA) Schottky barrier diode

PMEG2010EA

FEATURES

• Forward current: 1 A • Reverse voltage: 20 V

• Ultra high-speed switching

· Very low forward voltage

• Very small plastic SMD package.

APPLICATIONS

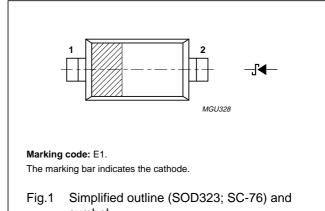
- Ultra high-speed switching
- · Voltage clamping
- · Protection circuits.

DESCRIPTION

Planar Maximum Efficiency General Application (MEGA) Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a SOD323 (SC-76) very small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



symbol.

ORDERING INFORMATION

TYPE	PACKAGE			
NUMBER	NAME	DESCRIPTION	VERSION	
PMEG2010EA	-	plastic surface mounted package; 2 leads	SOD323	

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	20	V
I _F	continuous forward current		_	1	А
I _{FSM}	non-repetitive peak forward current	t _p = 8.3 ms half sinewave; JEDEC method	_	5	А
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		_	125	°C
T _{amb}	operating ambient temperature		–65	+125	°C

2004 Feb 06 2

Low V_F (MEGA) Schottky barrier diode

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	continuous forward voltage	see Fig.2; note 1			
		I _F = 10 mA	240	270	mV
		I _F = 100 mA	300	350	mV
		I _F = 1000 mA	480	550	mV
I _R	continuous reverse current	see Fig.3; note 1			
		V _R = 5 V	5	10	μΑ
		V _R = 8 V	7	20	μΑ
		V _R = 15 V	10	50	μΑ
C _d	diode capacitance	V _R = 5 V; f = 1 MHz; see Fig.4	19	25	pF

Note

1. Pulsed test: t_p = 300 μ s; δ = 0.02.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	220	K/W
		note 2	180	K/W

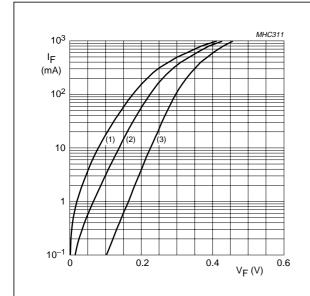
Notes

- 1. Device mounted on an FR4 printed-circuit board with Cu clad 10 x 10 mm.
- 2. Device mounted on an FR4 printed-circuit board with Cu clad 40 x 40 mm.

Low V_F (MEGA) Schottky barrier diode

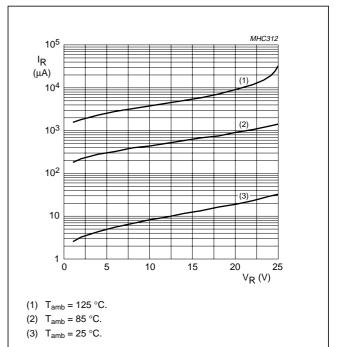
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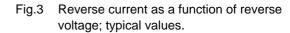
GRAPHICAL DATA

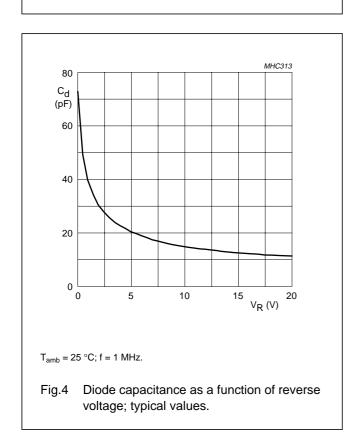


- (1) $T_{amb} = 125 \, ^{\circ}C$.
- (2) $T_{amb} = 85 \,^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.2 Forward current as a function of forward voltage; typical values.







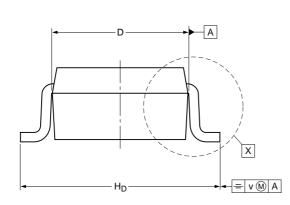
Low V_F (MEGA) Schottky barrier diode

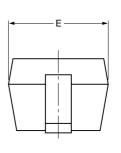
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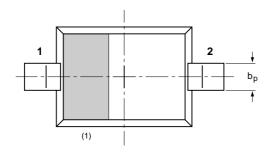
PACKAGE OUTLINE

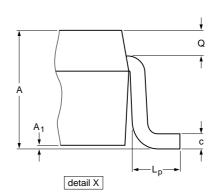
Plastic surface mounted package; 2 leads

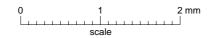
SOD323











DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			99-09-13 03-12-17

Low V_F (MEGA) Schottky barrier diode

PMEG2010EA

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Printed in The Netherlands

R76/02/pp7

Date of release: 2004 Feb 06

Document order number: 9397 750 12626

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